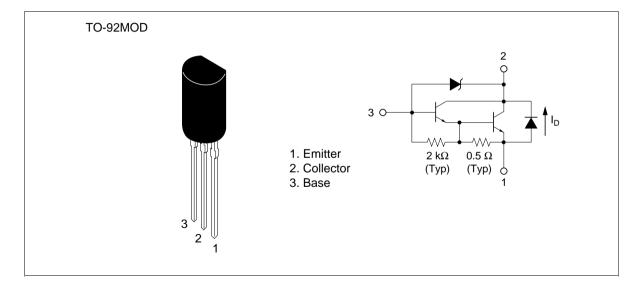
Silicon NPN Epitaxial, Darlington

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Application

Low frequency power amplifier

Outline





Absolute Maximum Ratings ($Ta = 25^{\circ}C$)

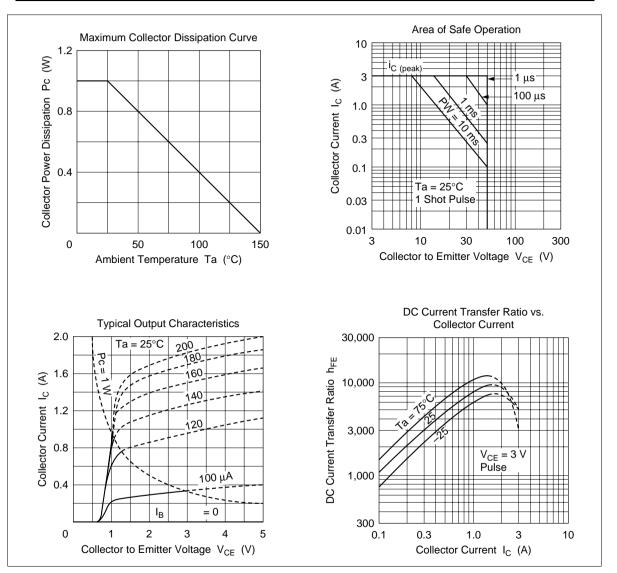
Item	Symbol	Ratings	Unit
Collector to base voltage	V _{CBO}	50	V
Emitter to base voltage	V _{EBO}	7	V
Collector current	Ι _c	1.5	А
Collector peak current	ic (peak)	3.0	А
Collector power dissipation	Pc	1.0	W
Junction temperature	Tj	150	°C
Storage temperature	Tstg	-55 to +150	°C
E to C diode forward current	Ι _D	1.5	А

Electrical Characteristics ($Ta = 25^{\circ}C$)

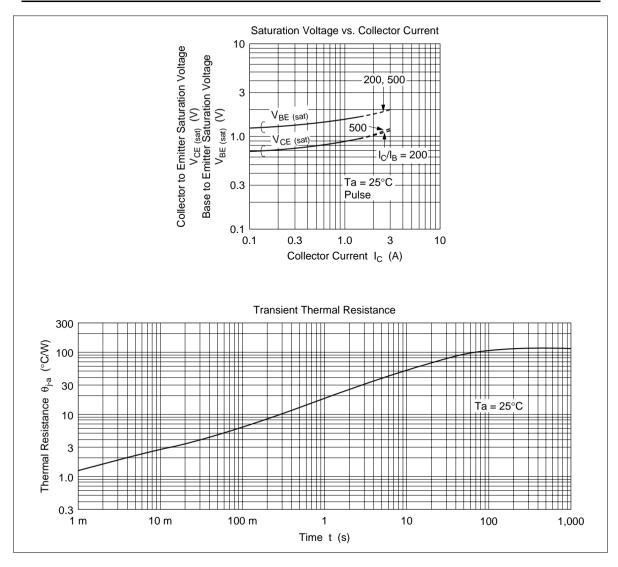
Item	Symbol	Min	Тур	Мах	Unit	Test conditions
Collector to base breakdown voltage (Zener breakdown voltage)	V _{(BR)CBO} (V _z)	50	60	70	V	$I_c = 0.1 \text{ mA}, I_e = \infty$
Collector to emitter breakdown voltage	$V_{(\text{BR})\text{CEO}}$	50	_	_	V	I_c = 10 mA, $R_{\scriptscriptstyle BE}$ = ∞
Emitter to base breakdown voltage	$V_{(\text{BR})\text{EBO}}$	7	_	_	V	$I_{\rm E} = 50$ mA, $I_{\rm C} = 0$
Collector cutoff current	I _{CEO}	_		10	μA	V_{CE} = 40 V, R_{BE} = ∞
DC current transfer ratio	h _{FE}	2000	_	10000		$V_{ce} = 3 V, I_c = 1 A^{*1}$
Collector to emitter saturation voltage	V _{CE(sat)1}	—	_	1.5	V	$I_{c} = 1 \text{ A}, I_{B} = 1 \text{ mA}^{*1}$
	V _{CE(sat)2}	_	_	2.0	V	$I_{c} = 1.5 \text{ A}, I_{B} = 1.5 \text{ mA}^{*1}$
Base to emitter saturation voltage	$V_{BE(sat)1}$	—	_	2.0	V	$I_c = 1 \text{ A}, I_B = 1 \text{ mA}^{*1}$
	V _{BE(sat)2}	—		2.5	V	$I_{\rm C} = 1.5 \text{ A}, I_{\rm B} = 1.5 \text{ mA}^{*1}$
E to C diode forward voltage	V _D			3.0	V	$I_{\rm D} = 1.5 \ {\rm A}^{*1}$

Note: 1. Pulse test

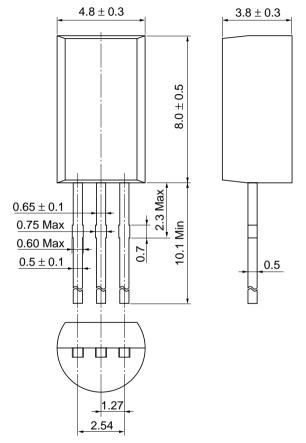
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Unit: mm



Hitachi Code	TO-92 Mod
JEDEC	_
EIAJ	Conforms
Weight (reference value)	0.35 g

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